

Integrated Thin Film Passive Components: A New Option for Miniature Flight Electronics

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Circuit designers can now utilize integrated passive components to replace discrete passive components placed around analog, digital, RF and optical circuitry. Further, the technology has evolved to the point where integrated devices can serve as an interposer for housing active devices thereby achieving even further performance improvements.

This presentation looks at today's integrated devices and documents size / weight advantages as well as improved electrical responses attractive to advanced semiconductors. Integrated product performance examples are documented and discussed.